



## Material Content Data Sheet



<b>Sales Product Name</b>	BTS443P			<b>Issued</b>	29. August 2013			
<b>MA#</b>	MA000267886							
<b>Package</b>	PG-TO252-5-11			<b>Weight*</b>	358.07 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.289	1.76	1.76	17564	17564
leadframe	non noble metal	iron	7439-89-6	0.205	0.06		571	
	inorganic material	phosphorus	7723-14-0	0.061	0.02		171	
	non noble metal	copper	7440-50-8	204.243	57.03	57.11	570397	571139
wire	non noble metal	aluminium	7429-90-5	1.917	0.54	0.54	5353	5353
encapsulation	organic material	carbon black	1333-86-4	1.359	0.38		3797	
	plastics	epoxy resin	-	23.791	6.64		66442	
	inorganic material	silicondioxide	60676-86-0	110.798	30.94	37.96	309428	379667
leadfinish	non noble metal	tin	7440-31-5	5.072	1.42	1.42	14166	14166
plating	non noble metal	nickel	7440-02-0	0.076	0.02		213	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	214
glue	plastics	Polyimide	26023-21-2	0.132	0.04	0.04	368	368
solder	noble metal	silver	7440-22-4	0.103	0.03		288	
	non noble metal	tin	7440-31-5	0.083	0.02		231	
	non noble metal	lead	7439-92-1	3.942	1.10	1.15	11010	11529
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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